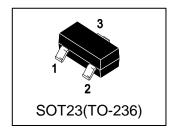


# LBAT54CLT1G S-LBAT54CLT1G

## Dual Series Schottky Barrier Diode

#### 1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 Volts (Typ) @ IF = 10 mAdc



# 3

#### 2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping		
LBAT54CLT1G	5C	3000/Tape&Reel		
LBAT54CLT3G	5C	10000/Tape&Reel		

#### 3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Reverse Voltage	VR	30	Vdc
Forward Current	IF	200	mAdc

#### 4. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation,	PD		
FR-5 Board (Note 1) @ TA = 25°C		225	mW
Derate above 25°C		1.8	mW/ºC
Thermal Resistance,	RΘJA	556	°C/W
Junction-to-Ambient(Note 1)			
Junction and Storage temperature	TJ,Tstg	-55~+125	°C

<sup>1.</sup>  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.

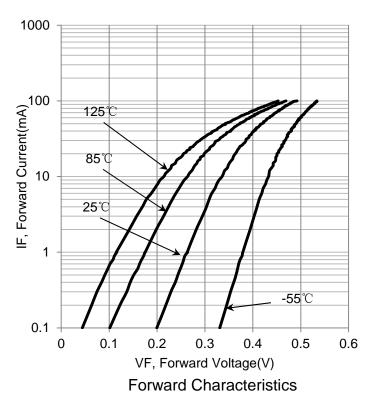


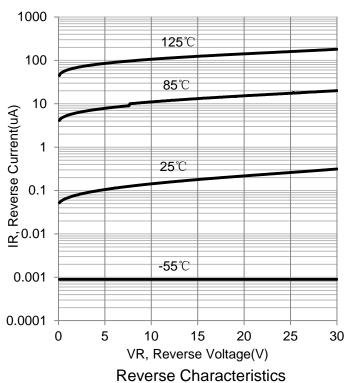
### 5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

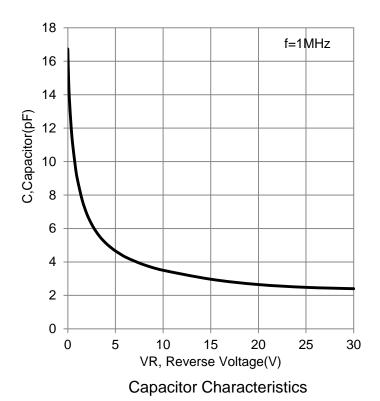
Characteristic	Symbol	Min.	Тур.	Max.	Unit
Reverse Breakdown Voltage	VBR				V
(IR = 10μAdc)	VBIX	30	-	-	
Reverse Voltage Leakage Current	IR				μA
(VR = 25Vdc)	IIX	-	0.5	2	
Diode Capacitance	СТ				pF
(VR =1.0V , f = 1.0 MHz)		-	-	10	
Forward Voltage	VF				V
(IF = 0.1 mAdc)		-	0.22	0.24	
(IF = 1 mAdc)		-	0.29	0.32	
(IF = 10 mAdc)		-	0.35	0.4	
(IF = 30 mAdc)		-	0.41	0.5	
(IF = 100 mAdc)		-	0.52	1	
Reverse Recovery Time	trr				ns
(IF = IR = 10 mAdc, IR(REC) = 1.0 mAdc)		-	-	5	
Repetitive Peak Forward Current	IFRM	-	-	300	mA
Non–Repetitive Peak Forward Current	IFSM				mA
(t < 1.0 s)		-	-	600	



#### 6. ELRCTRICAL CHARACTERISTICS CURVES





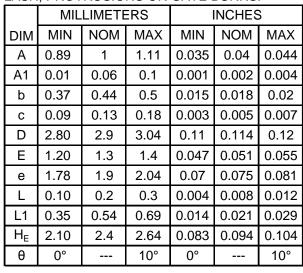


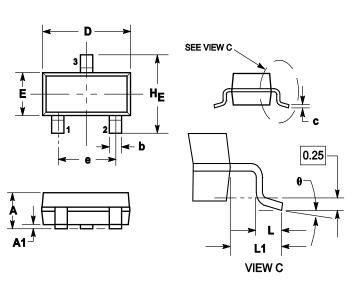


#### 7.OUTLINE AND DIMENSIONS

#### Notes:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.





#### 8.SOLDERING FOOTPRINT

